REVISIONS DATE **APPROVED** DESCRIPTION LTR Remove vendor 04713 for 01 package 13 MAR. from drawing. 1987 Add vendor 01295 for 02 package. Convert to new drawing format. Change  $I_{OS}$ ,  $I_{CC}$ ,  $f_{MAX}$ ,  $I_{IL}$ ,  $R_{L}$ , subgroups 10, 11, and propagation REV PAGE С С С REV **REV STATUS** 9 10 12 OF PAGES PAGES 3 4 5 6 2 ITARY DRAWING **Defense Electronics** This drawing is available for use by **Supply Center** all Departments and Agencies of the Dayton, Ohlo Department of Defense TITLE: MICROCIRCUITS, DIGITAL, LOW POWER SCHOTTKY, TTL, COUNTER, MONOLITHIC Original date of drawing: SILICON CODE IDENT. DWG SIZE 80018 19 Jan 1981 14933 Α 13 REV OF AMSC N/A PAGE 1 C 5962-E254

DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

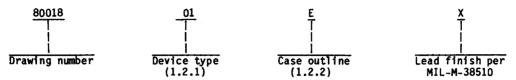
DESC FORM 193

MAY 86

1	SC	UDI

1.1 Scope. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of  $\overline{\text{MIL}}$ -STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".

1.2 Part number. The complete part number shall be as shown in the following example:



1.2.1 Device types. The device types shall identify the circuit function as follows:

Device type	Generic number	Circuit
01	54L S168	Synchronous 4-bit up/down decade counter
02	54L S169	Synchronous 4-bit up/down binary counter

1.2.2 <u>Case outlines</u>. The case outlines shall be as designated in appendix C of MIL-M-38510, and as follows:

Outline letter	<u>Case outline</u>			
E F 2	D-2 (16-pin, 1/4" x 7/8"), dual-in-line package F-5 (16-pin, 1/4" x 3/8"), flat package C-2 (20-terminal, .350" x .350"), square chip carrier package			

1.3 Absolute maximum ratings.

1.4 Recommended operating conditions.

1/ Must withstand the added P<sub>D</sub> due to short circuit tests (e.g., I<sub>OS</sub>).
2/ When a thermal resistance for this case is specified in MIL-M-38510, appendix C, that value shall supersede the value specified herein.

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## 2. APPLICABLE DOCUMENTS

2.1 Government specification and standard. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

### **SPECIFICATION**

MTI TTARY

MIL-M-38510 - Microcircuits, General Specification for.

### **STANDARD**

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

## 3. REQUIREMENTS

- 3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.
- $3.2\,$  Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
  - 3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.
  - 3.2.2 Truth tables. The truth tables shall be as specified on figure 2.
  - 3.2.3 Logic diagrams. The logic diagrams shall be as specified on figure 3.
  - 3.2.4 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full recommended case operating temperature range.
- 3.4 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in 6.4 herein.
- 3.5 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in 6.4. The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall state that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.6 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.
- 3.7 Notification of change. Notification of change to DESC-ECS shall be required in accordance with MIL-STD-883 (see 3.1 herein).

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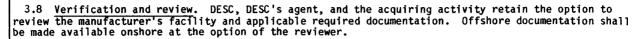
	IABLE	I. Elec	ctrical per	rformance	characte	ristics.				
T+	C	rmbol   Conditions   Group   Group   Group   Group   Unless Otherwise specified   Subgroup   Group   G			Limits		T 11m2			
Test	Symbol   		-55 C < unless o	T <sub>C</sub> < +125 therwise s	C, pecified	l (	Group A ubgroups		   Max   	Uni
High level output voltage	I V <sub>OH</sub>	I OH =	4.5 V -400 μA	AIH =	0.7 V 2.0 V		1, 2, 3	2.5   	     	٧
ow level output voltage	I V <sub>OL</sub>	V <sub>CC</sub> = 4	1.5 V 1 mA	AIT =	2.0 V 0.7 V	1	1, 2, 3	 	0.4	٧
Input clamp voltage	A <sup>IC</sup>	V <sub>CC</sub> = 4	4.5 V 25°C	IIN =	-18 mA	 	1		-1.5	٧
digh level input current	I <sub>IH1</sub>   	VIN = 2	5.5 V <u>1</u> / 2.7 V	count	-up, -down, c	load,	1, 2, 3		20	μА
-		  VIN = 3  VCC = 3	5.5 V <u>1</u> / 2.7 V	ET		1   1   	1, 2, 3		40	μА
·	I <sub>IH3</sub>	  A <sup>IN</sup> = ;  A <sup>CC</sup> = ;	5.5 V <u>1</u> /	count	-up, -down, c	load,   1	., 2, 3		100	μА
- !		V <sub>IN</sub> = 5	5.5 V <u>1</u> /	ET		1	., 2, 3		200	μА
ow level input current	I <sub>IL1</sub>	ACC = 2	5.5 V <u>2</u> /	Data	· · · · · · · · · · · · · · · · · · ·	1	1, 2, 3		-400	μА
	I <sub>IL2</sub>	  AIN = (	).4 V	Clock	, L, dow	n/up			-400	
_	I <sub>IL3</sub>	  V <sub>CC</sub> = 5	5.5 V <u>2</u> /	EP		1	, 2, 3	;	-385	μΑ
	I <sub>IL4</sub>	V <sub>IN</sub> = 0	).4 V	ET					-760	
Short-circuit output     circuit	<sup>1</sup> 0S	V <sub>OUT</sub> =	5.5 V <u>3/</u> 0.0 V			1	, 2, 3	-15 	-130	mA
Supply current	Icc	VCC = 5	5.5 V			1	, 2, 3		45   	mA
see footnotes at end of 1	able.		T	[ con= :=	ENT NO	1 5	10			
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TABI	E I. <u>E</u> 1	ectrical performance characteristics -	Continued.			
Test	Symbol	Conditions -55°C < T <sub>C</sub> < +125°C, unless otherwise specified	Group A T  subgroups		ts Max	Γ Unit
Functional tests	]		7			
Maximum input A 4/ clock, or count up	f <sub>MAX</sub>		9 (	20		MHz
	 	CL = 50 pF ±10%	10, 11	12		 
Propagation delay time, high-to-low-level	t <sub>PHL1</sub>		9		26	l ns
clock to Q	 	C <sub>L</sub> = 50 pF ±10%	10, 11		37	ns
Propagation delay time, low-to-high-level	t <sub>PLH2</sub>		9		26	l ns
clock to Q	clock to Q	 	10, 11		37	ns
Propagation delay time, high-to-low-level	t <sub>PHL2</sub>		9		28	l ns
ET to TC 4/	 	C_ = 50 pF ±10%	10, 11		   40 	l ns
Propagation delay time, low-to-high-level	t <sub>PLH3</sub>	T   	9		28	l ns
ET to TC 4/	  -  -	 	10, 11		   40 	i ns
Propagation delay time, high-to-low, counts up	t <sub>PHL3</sub>	T   	9		   73 	l I ns I
and down to $Q$ , $U/\overline{D}$ to $TC$ $4/$	 	 	10, 11		102 	l I ns I
Propagation delay time, low-to-high, counts up	l t <sub>PLH4</sub>	†   	9		1 38 1	l ns
and down to Q, $U/\overline{D}$ to TC $\underline{4}/$	   		10, 11		53.2	ns

not exceed one second. Propagation delay time testing and maximum clock frequency testing may be performed using either  $C_{L}=15$  pF or  $C_{L}=50$  pF. However, the manufacturer must certify and guarantee that the microcircuits meet the switching test limits specified for a 50 pF load.

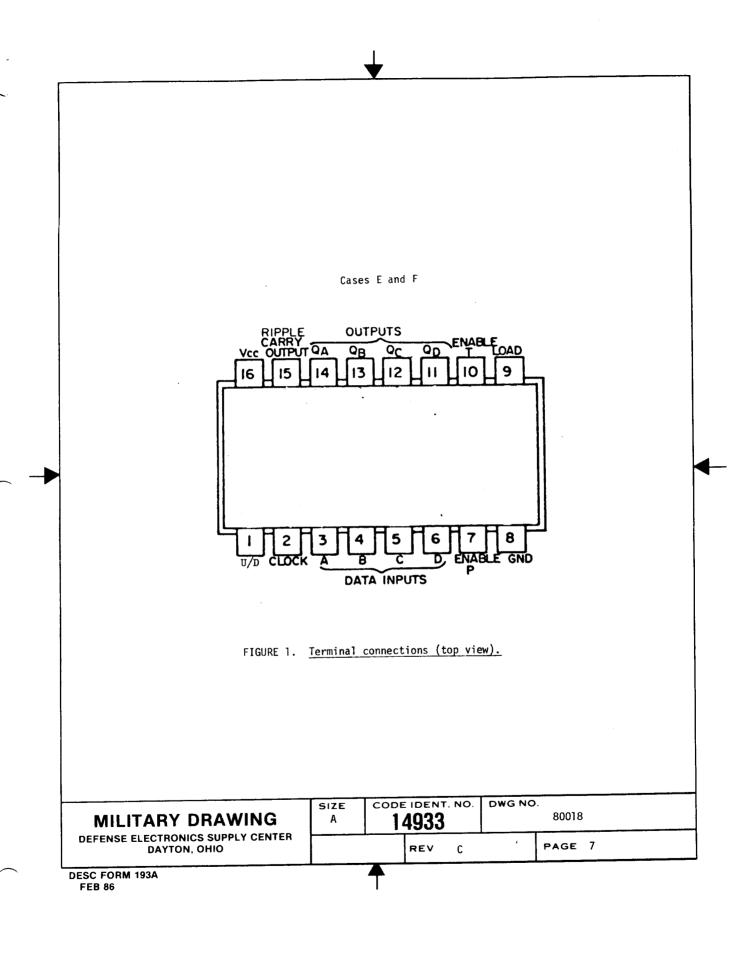
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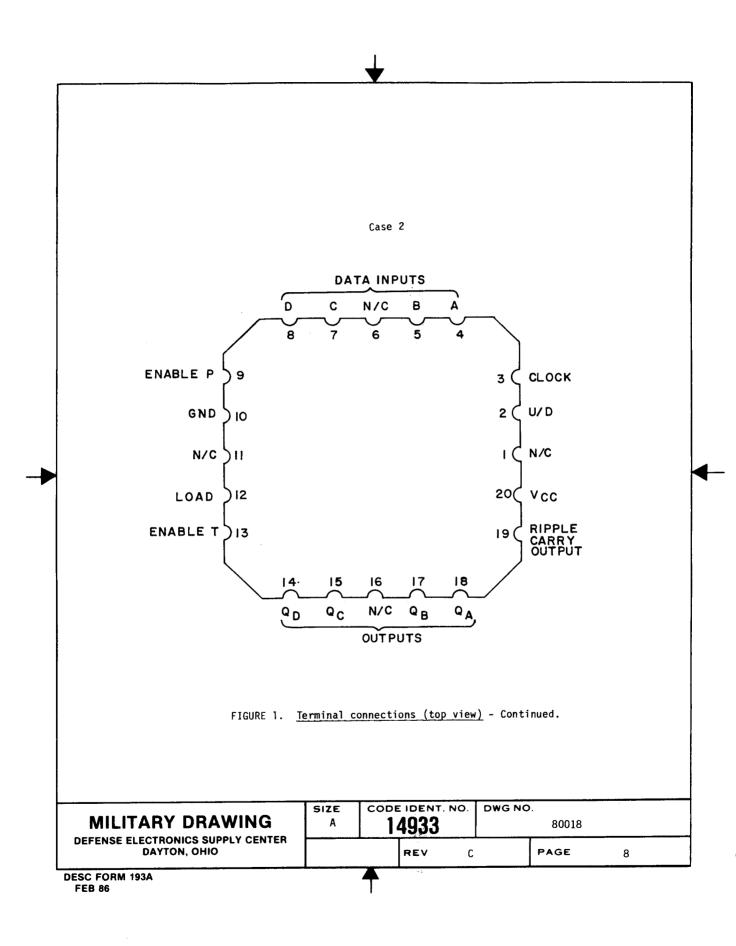
<sup>1/</sup> All unspecified inputs grounded.
2/ All unspecified inputs at 5.5 volts.
3/ Not more than one output should be shorted at a time and duration of short circuit condition should



- 4. QUALITY ASSURANCE PROVISIONS
- 4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).
- 4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
  - a. Burn-in test (method 1015 of MIL-STD-883).
    - Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
    - (2)  $T_A = +125^{\circ}C$ , minimum.
  - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
  - 4.3.1 Group A inspection.
    - a. Tests shall be as specified in table II herein.
    - b. Subgroups 4, 5, 6, and 8 in table I, method 5005 of MIL-STD-883 shall be omitted.
    - c. Subgroup 7 tests shall verify the truth tables.
  - 4.3.2 Groups C and D inspections.
    - a. End-point electrical parameters shall be as specified in table II herein.
    - b. Steady-state life test (method 1005 of MIL-STD-883) conditions:
      - Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
      - (2)  $T_A = +125^{\circ}C$ , minimum.
      - (3) Test duration: 1,000 hours, except as permitted by appendix B of MIL-M-38510 and method 1005 of MIL-STD-883.

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Device type 02 UP COUNT SEQUENCE TABLE

	De	vice	type 0	1
UP	cou	NT SE	QUENCE	TABLE
				0

	01 000111 02402112						
Q <sub>A</sub> (LSB	Q <sub>B</sub>	Q <sub>C</sub>	Q <sub>D</sub> (MSB)				
L	L	L	L				
Н	L	L	L				
L	Н	L	L				
Н	Н	L	L				
L	L	Н	L				
Н	L	Н	L				
F	Н	н	L				
Н	Н	Н	L				
L	L	L	Н				
н	L	L	Н				

Q <sub>A</sub> (LSB)	Q <sub>B</sub>	QC	Q <sub>D</sub> (MSB)
L	L	L	L
н	L	L	L
L	Н	L	
н	Н	L	L
L	L	н	L
Н	L	н	L
L	н	н	
н	Н	Н	L
L	L	L	н
Н	L		Н
L	Н	L L	н
Н	Н	L	н
L	L	н	н
н	L	н	н
L	Н	Н	н
н	Н	Н	Н

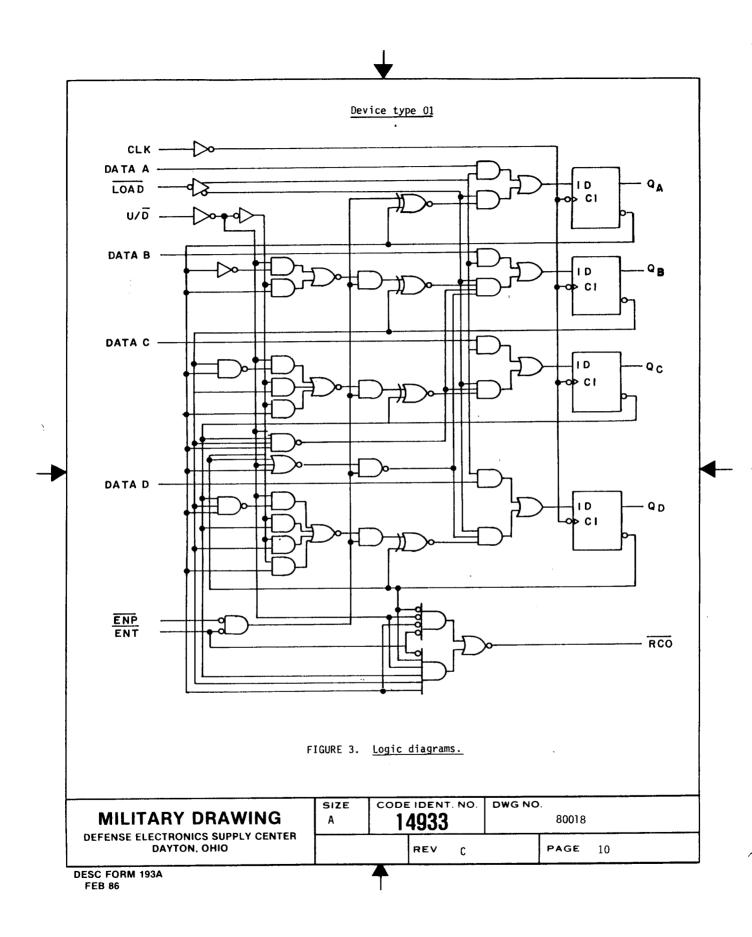
Device types 01 and 02 MODE SELECT TABLE

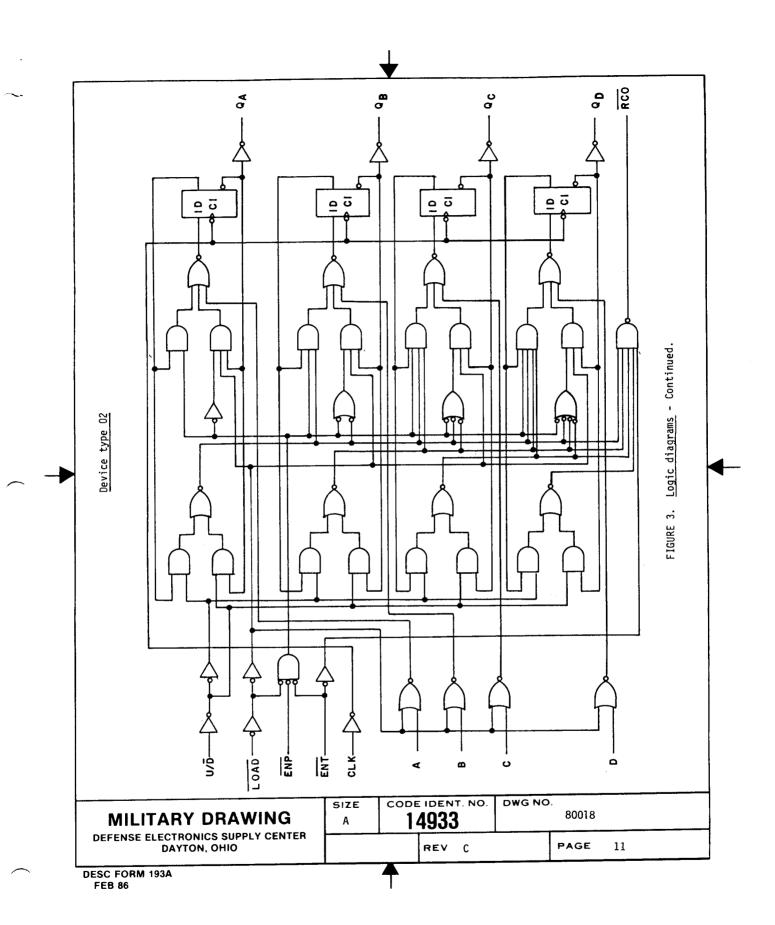
ī	ĒΡ	ĒŦ	U/D	Action on Rising Clock Edge	
L	χ	Х	Х	Load $(D_n \rightarrow Q_n)$	
Н	L	L	н	Count Up (increment)	
н	L	L	L	Count Down (decrement)	
Н	Н	Х	Х	No Change (Hold)	
н	Х	Н	Х	No Change (Hold)	

H = High voltage level
L = Low voltage level
X = Don't care

FIGURE 2. Truth tables.

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# TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups   (per method     5005, table I)
Interim electrical parameters (method 5004)	
Final electrical test parameters   (method 5004)	1*, 2, 3, 9
Group A test requirements   (method 5005)	1, 2, 3, 7, 9, 10, 11**
Groups C and D end-point   electrical parameters   (method 5005) 	1, 2, 3

\* PDA applies to subgroup 1.

\*\* Subgroups 10 and 11, if not tested, shall be guaranteed to the specified limits in table I.

### 5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

### 6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.

# 6.2 Replaceability. Replaceability is determined as follows:

- a. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- b. When a QPL source is established, the part numbered device specified in this drawing will be replaced by the microcircuit identified as part number M38510/31505B-- or M38510/31506B--.
- 6.3 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone 513-296-5375.

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6.4 Approved source of supply. An approved source of supply is listed herein. Additional sources will be added as they become available. The vendor listed herein has agreed to this drawing and a certificate of compliance (see 3.5 herein) has been submitted to DESC-ECS.

Military drawing part number	Vendor CAGE number	Vendor   similar part   number <u>1</u> /	Replacement  military specification   part number
8001801EX	<u>2</u> /	  54LS168/BEBJC	M38510/31505BEX
8001801FX	<u>2</u> /	54LS168/BFBJC	M38510/31505BFX
8001802EX <u>3</u> /	01295	  SNJ54LS169BJ 	M38510/31506BEX
8001802FX	01295	I  SNJ54LS169BW	M38510/31506BFX
80018022X	01295	  SNJ54LS169FK	M38510/31506B2X

<sup>2/</sup> Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

2/ No longer available from approved source.3/ Inactive for new design. Use QPL 38510 products.

**Vendor CAGE** number

Vendor name and address

01295

Texas Instruments P. O. Box 6448 Midland, TX 79701

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